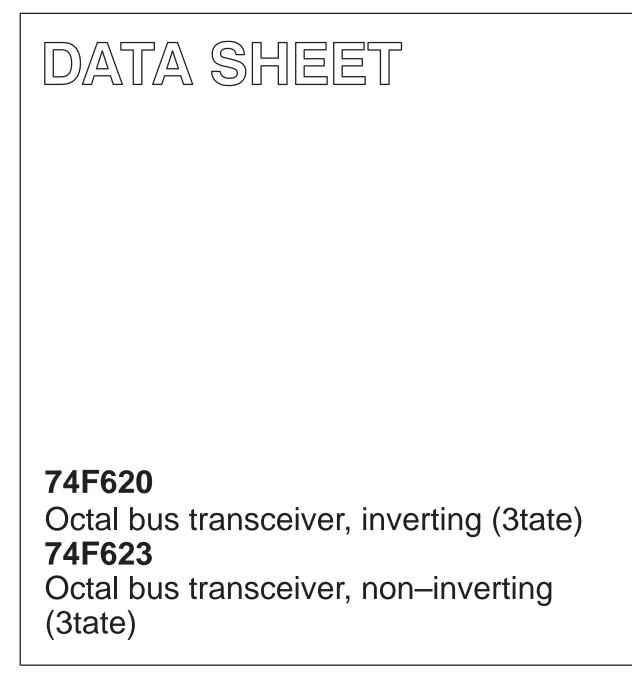
INTEGRATED CIRCUITS



Product specification

1989 Apr 06

IC15 Data Handbook



74F620/74F623

74F620 Octal Bus Transceiver, Inverting (3-State) 74F623 Octal Bus Transceiver, Non-Inverting (3-State)

FEATURES

- High-impedance NPN base inputs for reduced loading (70μA in High and Low states)
- Ideal for applications which require high output drive and minimal bus loading
- Octal bidirectional bus interface
- 3-State buffer outputs sink 64mA and source 15mA
- 74F620, inverting
- 74F623, non-inverting

DESCRIPTION

The 74F620 is an octal transceiver featuring inverting 3-State bus-compatible outputs in both send and receive directions. The outputs are capable of sinking 64mA and sourcing up to 15mA, providing very good capacitive drive characteristics. The 74F623 is a non-inverting version of the 74F620.

These octal bus transceivers are designed for asynchronous two-way communication between data buses. The control function implementation allows for maximum flexibility in timing.

These devices allow data transmission from the A bus to the B bus or from the B bus to the A bus depending upon the logic levels at the

INPUT AND OUTPUT LOADING AND FAN-OUT TABLE

Enable inputs ($\overline{\text{OEBA}}$ and OEAB). The Enable inputs can be used to disable the device so that the buses are effectively isolated.

The dual-enable configuration gives the 74F620 and 74F623 the capability to store data by the simultaneous enabling of \overline{OEBA} and OEAB. Each output reinforces its input in this transceiver configuration. Thus, when both control inputs are enabled and all other data sources to the two sets of the bus lines are at high impedance, both sets of bus lines (16 in all) will remain in their last states.

TYPE	TYPICAL PROPAGATION DELAY	TYPICAL SUPPLY CURRENT (TOTAL)
74F620	3.5ns	80mA
74F623	4.5ns	105mA

ORDERING INFORMATION

DESCRIPTION	$\begin{array}{l} \text{COMMERCIAL RANGE} \\ \text{V}_{CC} = 5\text{V} \pm 10\%, \\ \text{T}_{amb} = 0^{\circ}\text{C to } + 70^{\circ}\text{C} \end{array}$	PKG DWG #		
20-pin plastic DIP	N74F620N, N74623N	SOT146-1		
20-pin plastic SOL	N74F620D, N74623D	SOT163-1		

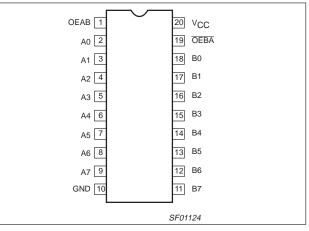
PINS	DESCRIPTION	74F(U.L.) HIGH/LOW	LOAD VALUE HIGH/LOW
A0 - A7, B0 - B7	Data inputs	3.5/1.16	70μΑ/70μΑ
OEBA, OEAB	Output Enable inputs	1.0/0.033	20μΑ/20μΑ
A0 - A7	Data outputs	150/40	3mA/24mA
B0 - B7	Data outputs	750/106.7	15mA/64mA

NOTE: One (1.0) FAST unit load is defined as: 20µA in the High state and 0.6mA in the Low state.

PIN CONFIGURATION – 74F620

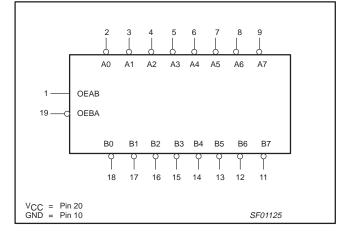
OEAB 1	20	VCC
A0 2	19	OEBA
A1 3	18	ВО
A2 4	17	B1
A3 5	16	B2
A4 6	15	B3
A5 7	14	B4
A6 8	13	B5
A7 9	12	B6
GND 10	11	B7
	SF0	1124

PIN CONFIGURATION - 74F623

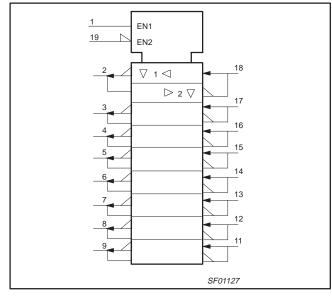


74F620/74F623

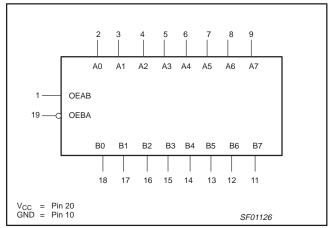
LOGIC SYMBOL - 74F620



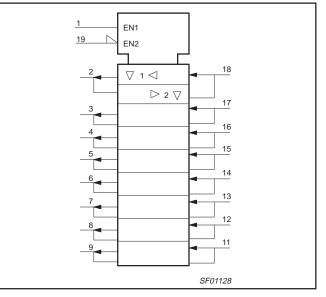
IEC/IEEE SYMBOL (IEEE/IEC) - 74F620



LOGIC SYMBOL - 74F623

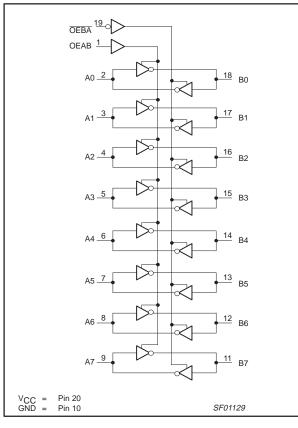


IEC/IEEE SYMBOL (IEEE/IEC) - 74F623



74F620/74F623

LOGIC DIAGRAM - 74F620

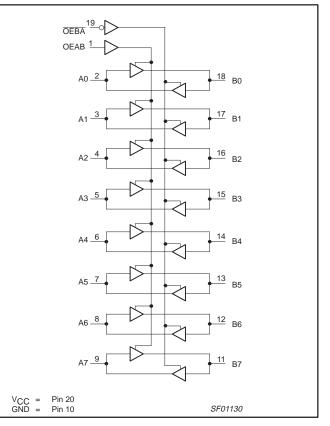


FUNCTION TABLE

INPU	JTS	OPERATING MODES				
OEBA	OEAB	74F620	74F623			
L	L	\overline{B} data to A bus	B data to A bus			
н	Н	\overline{A} data to B bus	A data to B bus			
н	L	Z	Z			
	н	\overline{B} data to A bus	B data to A bus			
	п	\overline{A} data to B bus	A data to B bus			

H = High voltage level L = Low voltage level X = Don't care Z = High impedance "off" state

LOGIC DIAGRAM - 74F623



74F620/74F623

ABSOLUTE MAXIMUM RATINGS

(Operation beyond the limits set forth in this table may impair the useful life of the device. Unless otherwise noted these limits are over the operating free-air temperature range.)

SYMBOL	PARAMETER		RATING	UNIT
V _{CC}	Supply voltage	-0.5 to +7.0	V	
V _{IN}	Input voltage	-0.5 to +7.0	V	
I _{IN}	Input current	-30 to +5	mA	
V _{OUT}	Voltage applied to output in High output state	–0.5 to +V _{CC}	V	
		A0–A7	48	mA
IOUT	Current applied to output in Low output state	128	mA	
T _{amb}	Operating free-air temperature range		0 to +70	°C
T _{stg}	Storage temperature range	-65 to +150	°C	

RECOMMENDED OPERATING CONDITIONS

CYMDOL	DADAL			LINUT		
SYMBOL	PARAN	IETER	MIN	NOM	MAX	UNIT
V _{CC}	Supply voltage		4.5	5.0	5.5	V
V _{IH}	High-level input voltage	2.0			V	
V _{IL}	Low-level input voltage			0.8	V	
I _{IK}	Input clamp current			-18	mA	
I		A0–A7			-3	mA
I _{ОН}	High-level output current			-15	mA	
1		A0–A7			24	mA
I _{OL}	Low-level output current	B0–B7			64	mA
T _{amb}	Operating free-air temperature range	0		70	°C	

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DC ELECTRICAL CHARACTERISTICS

(Over recommended operating free-air temperature range unless otherwise noted.)

SYMBOL	PARA	METER		TEST	MIN	TYP NO TAG	MAX	UNIT		
			A0–A7			±10%V _{CC}	2.4			V
		ltogo	B0–B7	$V_{CC} = MIN,$ $V_{IL} = MAX,$	I _{OH} = -3mA	±5%V _{CC}	2.7	3.3		V
V _{OH}	High-level output vo	Jilage	B0-B7	$V_{IH} = MIN$	I _{OH} = -15mA	$\pm 10\% V_{CC}$	2.0			V
			D0-D7		10H = -13111A	±5%V _{CC}	2.0			V
			A0–A7		I _{OL} = 24mA	±10%V _{CC}		0.35	0.50	V
V _{OL}	Low-level output vo	ltane		$V_{CC} = MIN,$ $V_{IL} = MAX,$		±5%V _{CC}		0.35	0.50	V
VOL		lage	B0–B7	$V_{IH} = MIN,$	I _{OL} = 48mA	±10%V _{CC}		0.38	0.55	V
			B0 B/		I _{OL} = 64mA	$\pm 5\% V_{CC}$		0.42	0.55	V
V _{IK}	Input clamp voltage	;		$V_{CC} = MIN, I_I$	= I _{IK}			-0.73	-1.2	V
I _I	Input current at ma	ximum	OEBA, OEAB	$V_{\rm CC} = 0.0 V, V$			100	μA		
	input voltage		others	V _{CC} = 5.5V, V			1	mA		
I _{IH}	High-level input cur	rent	OEBA, OEAB	V _{CC} = MAX, \			20	μΑ		
IIL	Low-level input cur	ent	only	V _{CC} = MAX, \	V _{CC} = MAX, V _I = 0.5V				-20	μΑ
I _{OZH} +I _{IH}	Off-state output cur High-level of voltag		A0–A7	$V_{CC} = MAX, V_I = 2.7V$					70	μA
I _{OZL} +I _{IL}	Off-state output cur Low-level of voltage		B0–B7	V _{CC} = MAX, \	_{CC} = MAX, V _I = 0.5V				-70	μA
1	Short-circuit output	cur-	A0–A7	V _{CC} = MAX			-60		-150	mA
I _{OS}	rent ^{NO TAG}		B0–B7	VCC = MAX			-100		-225	mA
			I _{ССН}		OEBA=OEAB: A0-A7=GND	=4.5V;		70	92	mA
		74F620	I _{CCL}	V _{CC} = MAX	OEBA=OEAB=4.5V; A0–A7=4.5V			84	110	mA
1	Supply current		I _{CCZ}		OEAB=GND; OEBA=A0–A7	=4.5V		84	110	mA
I _{CC} (total)	(total)		I _{CCH}		OEBA=OEAB A0–A7=4.5V	OEBA=OEAB=4.5V; A0–A7=4.5V		110	140	mA
		74F623	I _{CCL}	V _{CC} = MAX	C = MAX OEBA=OEAB=4.5V; A0-A7=GND			110	140	mA
			I _{CCZ}]	OEAB=GND; OEBA=A0-A7=4.5V			99	130	mA

NOTES:

1. For conditions shown as MIN or MAX, use the appropriate value specified under recommended operating conditions for the applicable type. 2. All typical values are at $V_{CC} = 5V$, $T_{amb} = 25^{\circ}C$. 3. Not more than one output should be shorted at a time. For testing I_{OS} , the use of high-speed test apparatus and/or sample-and-hold

3. Not more than one output should be shorted at a time. For testing I_{OS}, the use of high-speed test apparatus and/or sample-and-hold techniques are preferable in order to minimize internal heating and more accurately reflect operational values. Otherwise, prolonged shorting of a High output may raise the chip temperature well above normal and thereby cause invalid readings in other parameter tests. In any sequence of parameter tests, I_{OS} tests should be performed last.

74F620/74F623

AC ELECTRICAL CHARACTERISTICS – 74F620

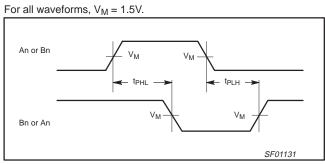
SYMBOL	PARAMETER	TEST CONDITION	l Ta	/ _{CC} = +5\ _{mb} = +25 0pF, R _L =	°C	V _{CC} = +5 T _{amb} = 0°C C _L = 50pF,	UNIT	
			MIN	ТҮР	MAX	MIN	MAX	
t _{PLH} t _{PHL}	Propagation delay An to Bn	Waveform 2	2.5 1.0	4.5 2.5	6.5 4.5	2.0 1.0	7.5 5.0	ns
t _{PLH} t _{PHL}	Propagation delay Bn to An	Waveform 2	2.5 1.0	4.5 2.5	6.5 4.5	2.0 1.0	7.5 5.0	ns
t _{PZH} t _{PZL}	Output Enable time to High or Low level, OEBA to An	Waveform 3 Waveform 4	3.0 4.0	7.5 7.5	10.5 10.5	2.5 3.5	11.5 11.5	ns
t _{PHZ} t _{PLZ}	Output Disable time to High or Low level, OEBA to An	Waveform 3 Waveform 4	2.5 2.0	4.5 4.5	7.5 7.0	2.0 1.5	8.0 7.5	ns
t _{PZH} t _{PZL}	Output Enable time to High or Low level, OEAB to Bn	Waveform 3 Waveform 4	4.5 4.5	7.5 7.5	10.5 10.0	4.0 4.0	11.5 11.0	ns
t _{PHZ} t _{PLZ}	Output Disable time to High or Low level, OEAB to Bn	Waveform 3 Waveform 4	3.0 4.0	6.5 6.5	9.5 9.5	2.5 3.5	10.5 10.5	ns

AC ELECTRICAL CHARACTERISTICS - 74F623

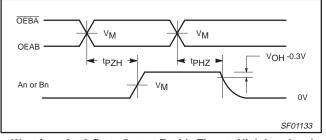
					LIM	ITS		
SYMBOL	PARAMETER	TEST CONDITION	\ T _{ai} C _L = 5	/ _{CC} = +5\ _{mb} = +25 0pF, R _L =	/ °C = 500Ω	V _{CC} = +5 T _{amb} = 0°C C _L = 50pF,	UNIT	
			MIN	ТҮР	MAX	MIN	MAX	
t _{PLH} t _{PHL}	Propagation delay An to Bn	Waveform 1	2.0 3.0	4.0 5.0	5.5 7.0	2.0 2.5	6.5 7.5	ns
t _{PLH} t _{PHL}	Propagation delay Bn to An	Waveform 1	2.0 2.5	4.0 4.5	5.5 6.5	2.0 2.5	6.5 7.5	ns
t _{PZH} t _{PZL}	Output Enable time to High or Low level, OEBA to An	Waveform 3 Waveform 4	5.0 5.0	8.5 7.5	10.5 9.5	5.0 5.0	12.0 10.0	ns
t _{PHZ} t _{PLZ}	Output Disable time to High or Low level, OEBA to An	Waveform 3 Waveform 4	2.5 2.5	4.5 4.5	6.5 6.5	2.5 2.5	7.5 7.0	ns
t _{PZH} t _{PZL}	Output Enable time to High or Low level, OEAB to Bn	Waveform 3 Waveform 4	5.0 4.5	8.0 7.0	10.0 9.0	5.0 4.5	11.5 9.5	ns
t _{PHZ} t _{PLZ}	Output Disable time to High or Low level, OEAB to Bn	Waveform 3 Waveform 4	3.0 4.0	6.0 7.0	8.5 9.0	3.0 4.0	10.0 10.0	ns

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AC WAVEFORMS

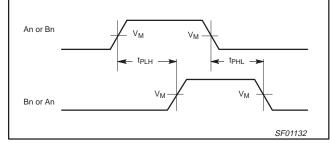


Waveform 1. For Inverting Outputs

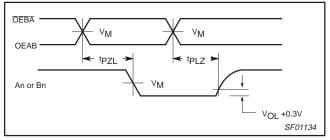


Waveform 3. 3-State Output Enable Time to High Level and Output Disable Time from High Level

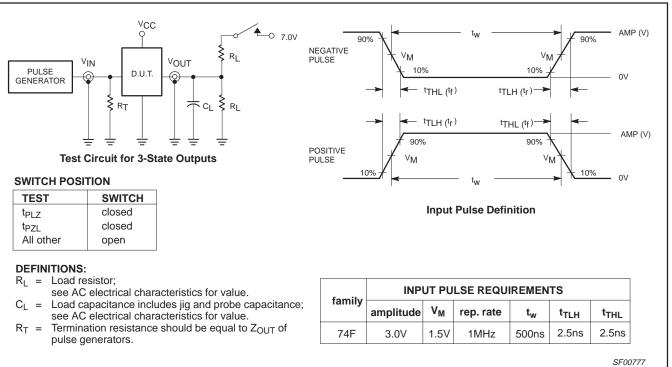
TEST CIRCUIT AND WAVEFORMS



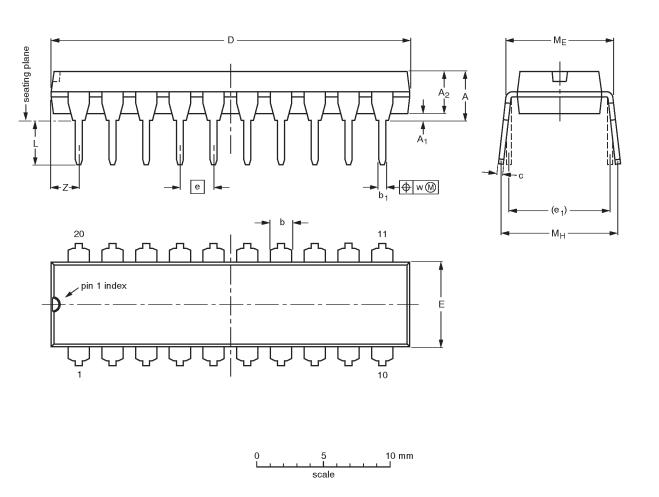




Waveform 4. 3-State Output Enable Time to Low Level and Output Disable Time from Low Level



DIP20: plastic dual in-line package; 20 leads (300 mil)



DIMENSIONS (inch dimensions are derived from the original mm dimensions)

UNIT	A max.	A ₁ min.	A ₂ max.	b	b ₁	c	D ⁽¹⁾	E ⁽¹⁾	e	e ₁	L	M _E	M _H	w	Z ⁽¹⁾ max.
mm	4.2	0.51	3.2	1.73 1.30	0.53 0.38	0.36 0.23	26.92 26.54	6.40 6.22	2.54	7.62	3.60 3.05	8.25 7.80	10.0 8.3	0.254	2.0
inches	0.17	0.020	0.13	0.068 0.051	0.021 0.015	0.014 0.009	1.060 1.045	0.25 0.24	0.10	0.30	0.14 0.12	0.32 0.31	0.39 0.33	0.01	0.078

Note

1. Plastic or metal protrusions of 0.25 mm maximum per side are not included.

OUTLINE		REFER	RENCES	EUROPEAN		ISSUE DATE
VERSION	IEC	JEDEC	EIAJ		PROJECTION	ISSUE DATE
SOT146-1			SC603			-92-11-17- 95-05-24

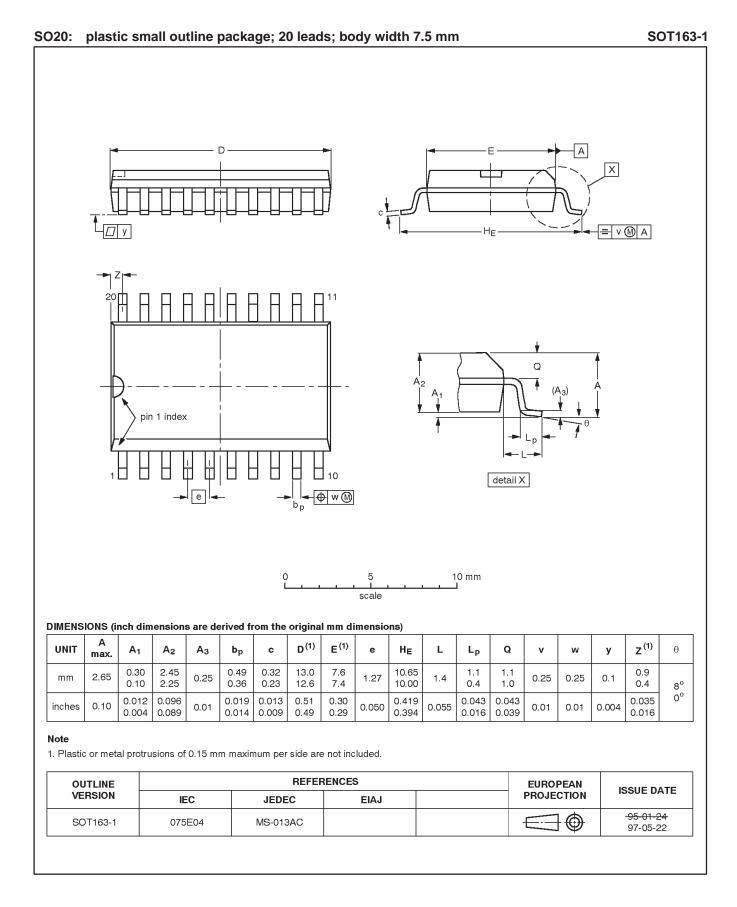
Product specification

SOT146-1

74F620, 74F623

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Product specification



74F620, 74F623

NOTES

74F620, 74F623

Data sheet status

Data sheet status	Product status	Definition ^[1]
Objective specification	Development	This data sheet contains the design target or goal specifications for product development. Specification may change in any manner without notice.
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